

NOTES:

1.MATERIAL:

HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL94V_0,COLOR:BLACK.

CONTACT: COPPER ALLOYS.

COVER: COPPER ALLOYS OR STEEL.

2.PLATING:

UNDERPLATE: NICKEL.

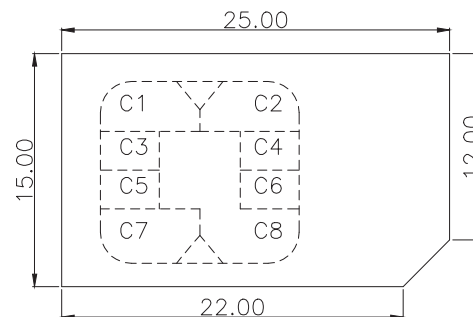
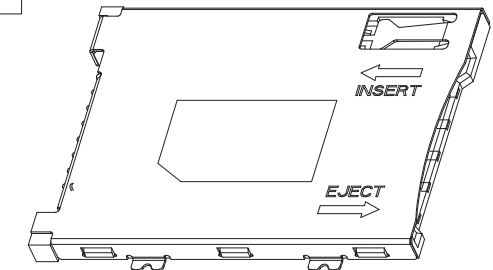
CONTACT AREA: GOLD OVER NICKEL.

SOLDER AREA: TIN OVER NICKEL.

3.MULTIMEDIA CARD COMPATIBLE

MINI SIM CARD

Pin No.	NAME
C1	VCC OF SIM
C2	GND OF SIM
C3	RST OF SIM
C4	VPP OF SIM
C5	CLK OF SIM
C6	I/O OF SIM
C7	DATO OF SIM
C8	MCMD OF SIM
C9	CARD DETECT SWITCH
C10	GND OF SIM



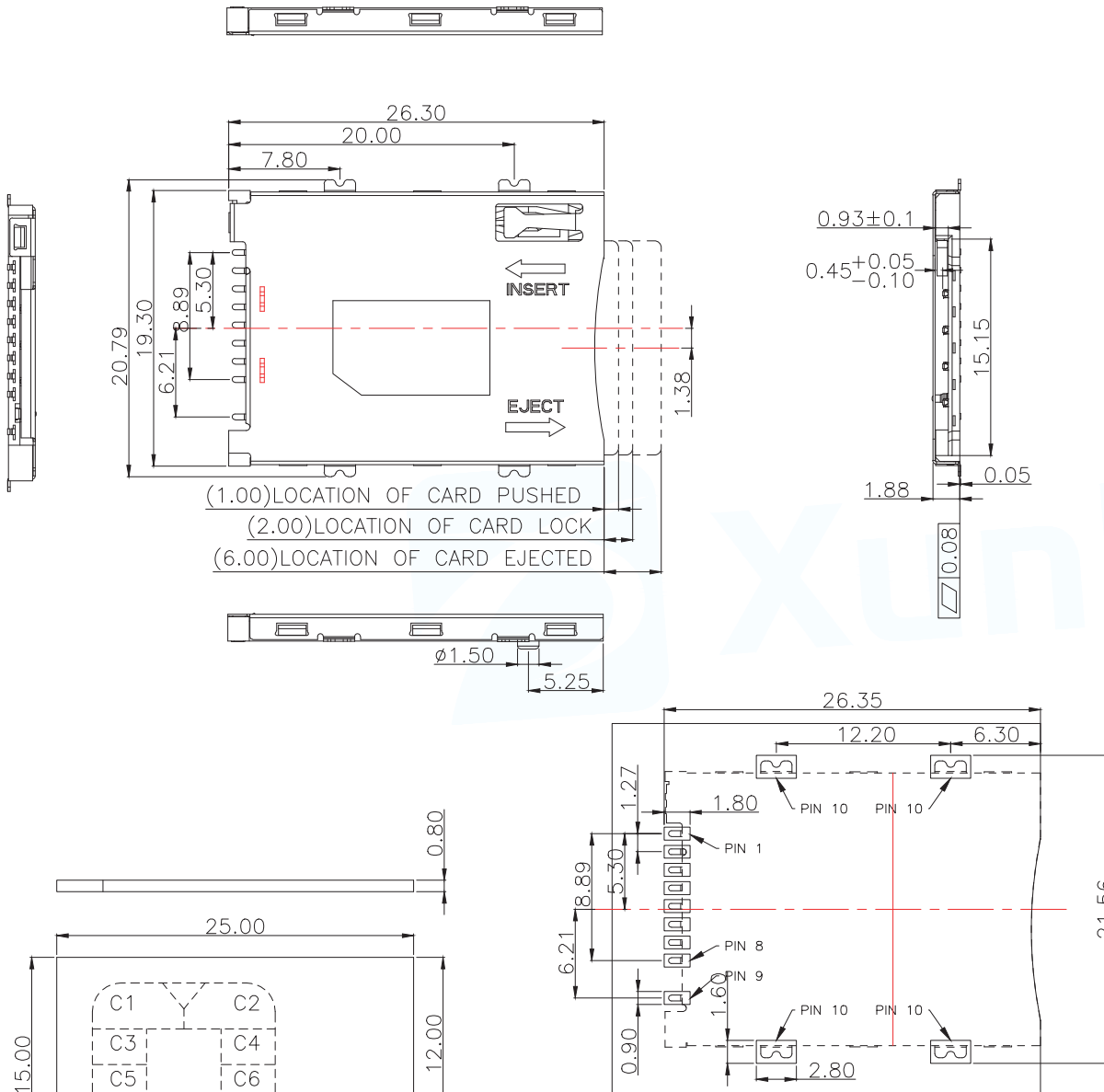
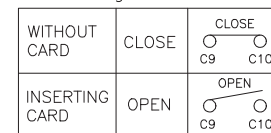
PAD AREA

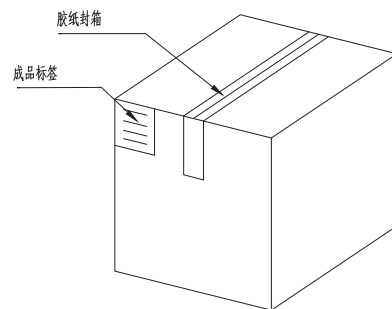
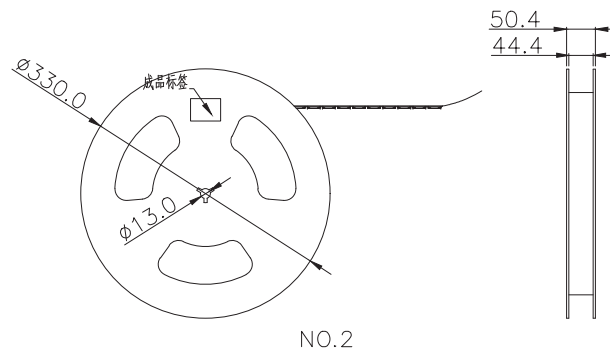
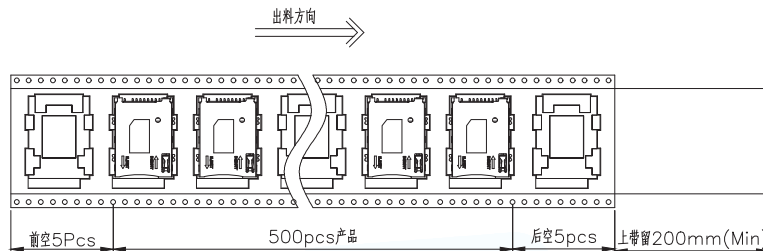
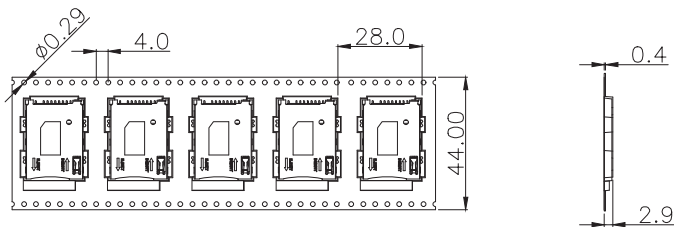
KEEP OUT AREA

RECOMMENDED PCB LAYOUT

GENERAL TOLERANCE ± 0.05

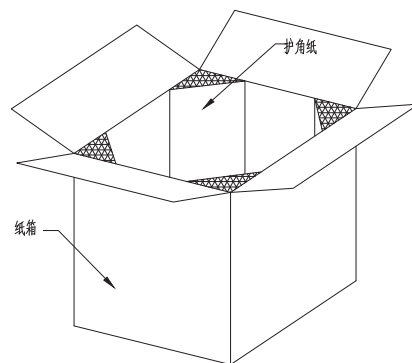
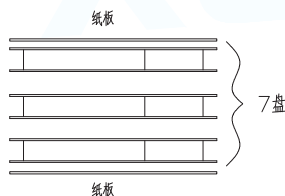
Circuit Diagram for Detect Switch





纸箱规格:350*350*385

NO.4



NO.3

1. 材质要求:

- 1.1 纸箱的材质为K=K;外形尺寸为35*35*38.5;
- 1.2 卷盘的材质为PS,卷盘的外形尺寸为 $\phi 330 \times 30.4$;
- 1.3 卷带的材质为PS,卷带的外形尺寸为20200*24.00*3.0mm;

2. 包装方式:

- 2.1 将卷带放入包装机后,前空5PCS,后放产品500PCS,再后空5PCS;上带留200mm长度。
- 2.2 将包装好的产品从包装机上取下并包装好,贴上内盘标签;
- 2.3 把累叠好的7盘叠放入纸箱中共计4.9Kset,上下放纸板,纸箱四个角塞护角纸;
- 2.4 把包装好的成品打包封箱,并在纸箱外贴上标签

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd		
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE:MINI SIM CARD PUSH PUSH 8+1P SMT无柱 H1.9	
			PAR	SIM-115-ARP9
DECIMALS:	ANGLES:		DWN	
X.X:±0.35	X.X':±3°		CHKD	
X.XX:±0.25	X.XX':±2°		APVD	
X.XXX:±0.15		CUSTOMER COPY	SCALE:1:1	UNIT:MM
			SIZE:A4	SHEET:1F1
				REV:A